

# CHO-BOND® 1030

## ONE COMPONENT FLEXIBLE ELECTRICALLY CONDUCTIVE SILICONE ADHESIVE

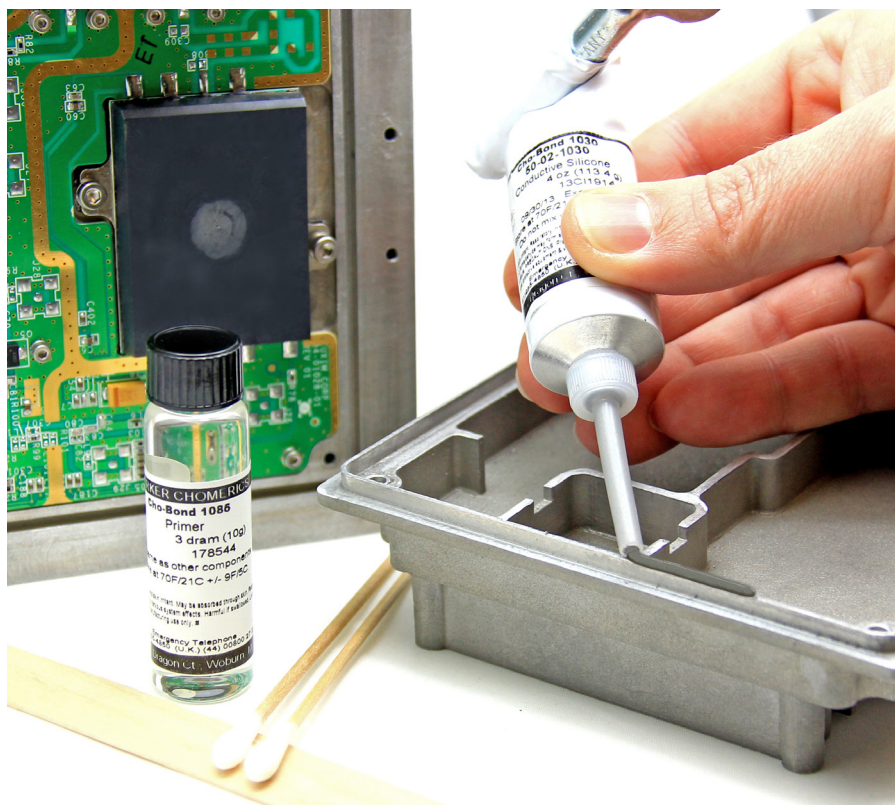


### Customer Value Proposition:

CHO-BOND 1030 is a silver plated copper filled, one-component conductive silicone designed for applications where a flexible, strong, conductive electrical bond must be achieved. CHO-BOND 1030 greatly simplifies the problem of bonding conductive silicone EMI gaskets to metal substrates. It is formulated for relatively small bond lines, less than 0.010 inches (0.25mm), and should not be used as an EMI caulk where bond lines are greater than 0.010 inches (0.25 mm).

No volatile organic compounds (VOCs) and minimal shrinkage upon curing make CHO-BOND 1030 a good choice for a variety of commercial and military applications. CHO-BOND 1030's moisture cure silicone polymer system allows it to cure to the touch in 24hrs and provides a robust conductive bond over a wide range of application temperatures.

For best adhesion results, CHO-BOND 1030 should be used in conjunction with CHO-SHIELD 1086 primer. Typical applications include bonding, repair, and attachment of EMI gaskets, and sealing around EMI vents and windows.



### Features and Benefits:

- One component
- Silver plated copper filler
- No VOCs
- Moisture cure silicone
- Non corrosive cure mechanism
- Medium paste
- Easy to use, no weighing or mixing required.
- Good conductivity 0.050 ohm-cm.
- Minimal shrinkage.
- Flexible, 30 minute working life, rapid skin formation, > 200 psi lap shear strength, 24 hr handling time, wide range of application temperatures. 1 week for full cure.
- No corrosive by-products generated during curing to damage substrate.
- Can be used on overhead or vertical surfaces.

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